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AMENDMENTS AND LISTING OF CLAIMS

1. (Currently Amended) A method for forming an electrical interconnect on an integrated lead suspension or suspension component of the type having a spring metal layer, a conductive lead layer having an upper surface and an insulating layer separating portions of the spring metal and conductive lead layers, including:

forming an aperture through at least the insulating layer and exposing the spring metal layer at an interconnect site;

applying an interconnect mask around the interconnect site;

electroplating a first conductive material on the spring metal layer at the interconnect site to form a plated interconnect, including building up the first conductive material over the spring metal layer to a height about equal to or greater than the upper surface of the conductive lead layer; and

not reflowing the plated interconnect; and

removing the interconnect mask.

2. (Currently Amended) The method of claim 1 and further including electroplating a second conductive material on the plated interconnect.

3. (Currently Amended) The method of claim 2 wherein electroplating the second conductive material on the plated interconnect includes electroplating the plated interconnect with non-corrosive metal.

4. (Currently Amended) The method of claim 2 wherein electroplating the second conductive material on the plated interconnect includes electroplating the plated interconnect with gold.

5. (Currently Amended) The method of claim 1 wherein electroplating the first conductive material includes forming a plated nickel or nickel alloy interconnect.

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6. (Currently Amended) The method of claim 1 ~~for forming a bond pad~~
interconnect wherein electroplating a first conductive material includes electroplating the
first conductive material on the spring metal layer and not in contact with the conductive lead
layer to form a plated bond pad interconnect that is electrically isolated from the conductive
lead layer.

7. (Currently Amended) The method of claim 1 wherein:
forming an aperture includes forming an aperture through the insulator layer and at
least one of the spring metal layer and conductive lead layer to expose portions
of the spring metal and conductive lead layers at the interconnect site; and
electroplating the first conductive material includes electroplating the first conductive
material on the spring metal layer at the interconnect site to form an electrical
interconnect between the spring metal layer and the conductive lead layer,
including causing the first conductive material to build up on the spring metal
layer, and with continuing build up to reach a thickness at which the first
conductive material electroplates onto and builds up on the conductive lead
layer.

8. (Canceled)

9. (Currently Amended) The method of claim 8 7 wherein:
forming an aperture includes forming an aperture through the insulator layer and the
spring metal layer but not the conductive lead layer; and
electroplating the first conductive material includes forming a spring metal side
interconnect.

10. (Currently Amended) The method of claim 8 7 and further including
electroplating a second conductive metal on exposed portions of the conductive lead layer at
the interconnect site before forming the spring metal side contact.

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11. (Currently Amended) The method of claim 8 7 wherein:
forming an aperture includes forming an aperture through the insulator layer and the
conductive lead layer but not the spring metal layer; and
electroplating the first conductive material includes forming a conductive lead side
interconnect.

12. (Currently Amended) The method of claim 1 and further including removing
oxide from exposed portions of the spring metal layer at the interconnect site before
electroplating the first conductive material to form the plated interconnect.

13. (Original) The method of claim 12 wherein removing oxide includes:
exposing the interconnect site to a plating metal bath; and
applying current to the interconnect site to perform an anodic clean.

14. – 17. (Canceled)

18. (Withdrawn) In an integrated lead suspension or suspension component of the
type having a conductive spring metal layer, a conductive lead layer and an insulator layer
between at least portions of the spring metal and conductive lead layers, an electrical
interconnect between the spring metal and conductive lead layers, including:
an aperture through the insulator layer and at least one of the spring metal and
conductive lead layers at an interconnect site; and
an electroplated conductive material interconnect extending between both the spring
metal layer and the conductive lead layer at the interconnect site.

19. (Withdrawn) The electrical interconnect of claim 18 wherein:

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the aperture includes an aperture through the spring metal and insulator layers exposing an interior surface of the conductive lead layer at the interconnect site; and

the electroplated interconnect includes conductive material plated over the spring metal layer and built up to extend into plated electrical contact with the interior surface layer of the conductive lead layer at the interconnect site.

20. (Withdrawn) The electrical interconnect of claim 18 wherein:

the aperture includes an aperture through the conductive lead and insulator layers exposing an interior surface of the spring metal layer at the interconnect site; and

the electroplated interconnect includes conductive material interconnect plated over the interior surface of the spring metal layer and built up to extend into plated electrical contact with the conductive lead layer at the interconnect site.

21. (Withdrawn) In an integrated lead suspension or suspension component of the type having a conductive spring metal layer, a conductive lead layer and an insulator layer between at least portions of the spring metal and conductive lead layers, an electrical bond pad interconnect including an electroplated conductive material pad on the spring metal layer at an interconnect site.

22. (Withdrawn) The bond pad interconnect of claim 21, wherein the conductive material pad is built up on the same side of the spring metal layer as the conductive lead layer and to a height generally equal to a height of the conductive lead layer.